

APPLICABLE STANDARD					
Rating	Operating Temperature Range	-55 °C to +85 °C ⁽¹⁾	Storage Temperature Range	-10 °C to +60 °C ⁽²⁾	
	Operating Humidity Range	Relative humidity 85 % max (Not dewed)	Storage Humidity Range	Relative humidity 85 % max (Not dewed)	
	Voltage	200 V AC	Applicable Cable	—	
	Current	1 A	Insulation	—	
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	
QT		AT			
CONSTRUCTION					
General Examination		Visually and by measuring instrument.		According to drawing.	
Marking		Confirmed visually.			
ELECTRIC CHARACTERISTICS					
Contact Resistance		100 mA (DC or 1000 Hz).		15 mΩ MAX .	
Insulation Resistance		500 V DC.		1000 MΩ MIN.	
Voltage Proof		650 V AC for 1 min.		No flashover or breakdown.	
MECHANICAL CHARACTERISTICS					
Mechanical Operation		100 times insertions and extractions.		1) Contact Resistance: 20 mΩ MAX. 2) No damage, crack and looseness of parts.	
Vibration		Frequency 10 to 55 Hz, single amplitude : 0.75 mm, 2 h in 3 directions.		1) No electrical discontinuity of 1 μs. 2) No damage, crack and looseness of parts.	
Shock		490 m/s ² , duration of pulse 11 ms at 3 times for 3 both axial directions.			
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)		Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.		1) Contact Resistance: 20 mΩ MAX. 2) Insulation Resistance: 1000 MΩ MIN. 3) No damage, crack and looseness of parts.	
Rapid Change of Temperature		Temperature -55 → +5 to +35 → +85 → +5 to +35 °C Time 30 → 10 to 15 → 30 → 10 to 15 min. Under 5 cycles.			
Corrosion Salt Mist		Exposed in 5 % salt water spray for 48 h.		1) Contact Resistance: 20 mΩ MAX. 2) No heavy corrosion.	
Sulphur Dioxide		Exposed in 10 PPM for 96 h. (Test standard: JEIDA 39)			
Resistance to Soldering Heat		Solder bath : solder temperature, 260 ± 5 °C for immersion,duration, 10 ± 1 s. (JISC5402-12-4, JISC60068-2-20) Soldering irons : 360°C for 5 s MAX.		No deformation of case of excessive looseness of the terminals.	
Solderability		Soldered at solder temperature, 245 ± 3 °C, for immersion duration, 3 s.		A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.	
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	1	DIS-F-00004353	HR.NAGAYASU	HT.YAMAGUCHI	20190301
REMARK (1) Temperature rise included when energized. (2) This storage indicates A long—term storage state For the unused product before the board mounted. Unless otherwise specified, refer to IEC-60512. Clerical corrections.			APPROVED	NH.NAKATA	20170410
			CHECKED	HT.YAMAGUCHI	20170410
			DESIGNED	HR.NAGAYASU	20170410
			DRAWN	HR.NAGAYASU	20170410
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELCX-375928-00-00
	SPECIFICATION SHEET		PART NO.	A3B- * PA-2DS(51)	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL621	1/1